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(54) **METHOD FOR PRODUCING WIRING
CIRCUIT BOARD**

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(71) Applicant: **NITTO DENKO CORPORATION,**
Osaka (JP)

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(72) Inventors: **Hayato TAKAKURA,** Osaka (JP);
Naoki SHIBATA, Osaka (JP); **Makoto**
TSUNEKAWA, Osaka (JP)

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(73) Assignee: **NITTO DENKO CORPORATION,**
Osaka (JP)

(57) **ABSTRACT**

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A method for producing a wiring circuit board includes a step of forming an insulating layer on one surface in a thickness direction of a substrate, a step of forming a plurality of wirings on one surface in the thickness direction of the insulating layer, a step of forming an opening portion including the plurality of wirings when projected in the thickness direction in the substrate, a step of forming a resist pattern having an opening portion having a pattern shape along the plurality of wirings on the other surface in the thickness direction of the insulating layer, a step of forming a metal support portion by depositing a metal material on the insulating layer inside the opening portion, and a step of removing the resist pattern.

(30) **Foreign Application Priority Data**

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